

AMENDMENTS TO THE CLAIMS:

1. (Currently Amended) ~~An electric terminal for an electronic device~~ A semiconductor device
for use on a printed circuit board, comprising:

a semiconductor chip having a thermal expansion coefficient different from a thermal expansion coefficient of the printed circuit board;

a lead member disposed on an internal electrode of the electronic device, at least a portion of said lead member being a conductor electrically connecting said external electrode and the internal electrode connected to the semiconductor chip;

an external electrode for electrically connecting said lead member with said printed circuit board; and

a support member disposed on the electronic device in the vicinity of semiconductor chip to surround said lead member for supporting,

wherein said support member contacts said external electrode at least upon application of an external thrust force which deforms said lead member.

2. (Currently Amended) ~~The electric terminal~~ The semiconductor device as defined in claim 1, wherein said support member is in contact with said external electrode upon application of no external thrust force.

3. (Currently Amended) ~~The electric terminal~~ The semiconductor device as defined in claim 1, wherein said support member is out of contact with said external electrode upon application of no external thrust force.

4. (Currently Amended) ~~The electric terminal~~ The semiconductor device as defined in claim 1, wherein said external electrode comprises ~~an external terminal, and wherein said external terminal includes~~ a solder ball.

5. (Currently Amended) ~~The electric terminal~~ The semiconductor device as defined in claim 1, wherein said external ~~terminal~~ electrode includes a core, at least a portion of which is covered by a solder coat.

6. (Currently Amended) ~~The electric terminal~~ The semiconductor device as defined in claim 1, wherein said external ~~terminal~~ electrode includes a central core ~~made of~~ comprising at least one conductor material and covered by a solder coat, said conductor material having a melting point higher than a melting point of said solder coat.

7. (Currently Amended) ~~The electric terminal~~ The semiconductor device as defined in claim 1, wherein said external ~~terminal~~ electrode includes a central core made of at least one conductor material and covered by a solder coat, said central core receiving therein an insulator sub-core.

8. (Currently Amended) ~~The electric terminal~~ The semiconductor device as defined in claim 1, wherein said lead member ~~is made of~~ comprises a conductor.

9. (Currently Amended) ~~The electric terminal~~ The semiconductor device as defined in claim 1, wherein said lead member includes a conductor body formed by plating.

10. (Currently Amended) ~~The electric terminal~~ The semiconductor device as defined in claim 1, wherein said lead member includes a conductor body formed separately from and connected to the electronic device.

11. (Currently Amended) ~~The electric terminal~~ The semiconductor device as defined in claim 1, wherein said lead member is formed by etching a metallic film.

12. (Currently Amended) ~~The electric terminal~~ The semiconductor device as defined in claim 1, wherein said lead member includes a wire.

13. (Currently Amended) ~~The electric terminal~~ The semiconductor device as defined in claim 1, wherein said lead member includes a wire covered by an insulator coat.

14. (Currently Amended) ~~The electric terminal~~ The semiconductor device as defined in claim 1, wherein said lead member ~~includes a conductor bump made of~~ comprises a conductive material including solder.

15. (Currently Amended) ~~The electric terminal~~ The semiconductor device as defined in claim 1, wherein said lead member includes an insulator body having a through-hole filled with a plating conductor.

16. (Currently Amended) ~~The electric terminal~~ The semiconductor device as defined in claim 1,

wherein said support member includes an insulator body patterned by a photolithographic technique.

17. (Currently Amended) ~~The electric terminal~~ The semiconductor device as defined in claim 1, wherein said support member ~~includes a resin body formed by~~ comprises a resin material configured by a transfer molding technique.

18. (Currently Amended) ~~The electric terminal~~ The semiconductor device as defined in claim 17, wherein said support member is made by etching said resin ~~body~~ material.

19. (Currently Amended) ~~The electric terminal~~ The semiconductor device as defined in claim 18, wherein said etching includes at least one of laser etching, wet etching and dry etching.

20. (Currently Amended) ~~The electric terminal~~ The semiconductor device as defined in claim 1, wherein said support member includes an insulator body having a through-hole through which said lead member passes.

21. (Currently Amended) ~~The electric terminal~~ The semiconductor device as defined in claim 1, wherein said support member is formed by patterning an insulator plate by an etching.

22. (Currently Amended) ~~The electric terminal~~ The semiconductor device as defined in claim 21, wherein said etching is either laser etching, wet etching or dry etching.

23. (Currently Amended) An electronic instrument comprising the ~~electric terminal~~ semiconductor device as defined in claim 1.

24-45 (Canceled)

46. (Currently Amended) ~~The electric terminal~~ The semiconductor device according to claim 1, wherein said support member partially surrounds said lead member to prevent excessive deformation of said lead member.

47. (Currently Amended) ~~The electric terminal~~ The semiconductor device according to claim 1, wherein said lead member for electrically connecting said external electrode is separately disposed from said support member when no external force is applied.

48. (Currently Amended) ~~The electric terminal~~ The semiconductor device according to claim 1, wherein said lead member is substantially parallel to said support member to isolate, electrically, said lead member ~~and~~ from said external electrode.

49. (Currently Amended) ~~The electric terminal~~ The semiconductor device according to claim 1, wherein said support member comprises a plurality of insulator poles disposed radially outside said lead member.

50. (Currently Amended) ~~The electric terminal~~ The semiconductor device according to claim 1, wherein said support member is separately disposed from said external electrode.